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Atty. Dkt. No. APPM007624/PPC/ECP/CKIM

THE PENDING CLAIMS:

1. (Previously Presented) An electrochemical plating cell, comprising:
 - a fluid basin configured to contain an electrolyte plating solution, the fluid basin having an anolyte fluid volume and a catholyte fluid volume;
 - a fluid tank in fluid communication with the fluid basin and being configured to supply the electrolyte plating solution thereto; and
 - an electrolyte solution stabilization device in fluid communication with the fluid tank, the stabilization device comprising:
 - a fluid container having a fluid inlet and a fluid outlet; and
 - an absorbent material positioned in the fluid container in a fluid path between the fluid inlet and the fluid outlet, wherein the absorbent material is configured to leach a solution additive into the electrolyte plating solution to maintain concentration of the solution additive within a processing window during an electrochemical plating process.
2. (Original) The plating cell of claim 1, wherein the absorbent material comprises at least one of charcoal, polypropylene, glass, minerals, ion-exchange resins, resins for chromatography, and combinations thereof.
3. (Original) The plating cell of claim 1, wherein the anolyte volume is separated from the catholyte volume by a cationic membrane.
4. (Original) The plating cell of claim 3, wherein the fluid outlet of the fluid container is in fluid communication with the catholyte container.
5. (Previously Presented) The plating cell of claim 2, wherein the absorbent material is configured to leach additives into the electrolyte solution when the concentration of the additives is less than a desired concentration and to absorb additives from the electrolyte solution when the concentration is greater than the desired concentration.

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6. (Original) The plating cell of claim 5, wherein the fluid container is positioned in a fluid conduit connecting the fluid basin to the fluid tank.

7. (Original) The plating cell of claim 5, wherein the fluid container is positioned in the fluid tank.

8. (Original) The plating cell of claim 5, further comprising a filter positioned between the fluid container and the fluid basin, the filter being configured to remove particulate matter emanating from the absorbent material from a fluid stream passing therethrough.

9 - 21: (Canceled)

22. (Previously Presented) An electrochemical plating cell, comprising:
a fluid basin configured to contain an electrolyte plating solution; and
an electrolyte solution stabilization device in fluid communication with the fluid basin, the stabilization device comprising:

a fluid container having a fluid inlet and a fluid outlet; and

an absorbent material positioned in the fluid container in a fluid path between the fluid inlet and the fluid outlet, wherein the absorbent material is configured to leach a solution additive into the electrolyte plating solution to maintain concentration of the solution additive within a processing window during an electrochemical plating process.

23. (Previously Presented) The cell of claim 22, wherein the absorbent material is configured to maintain the concentration of one solution additive when the electrolyte plating solution comprises two or more solution additives.

24. (Previously Presented) The plating cell of claim 22, wherein the absorbent material comprises at least one of charcoal, polypropylene, glass, minerals, ion-exchange resins, resins for chromatography, and combinations thereof.

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25. (Previously Presented) The plating cell of claim 22, wherein an anolyte volume is separated from a catholyte volume by a cationic membrane.
26. (Previously Presented) The plating cell of claim 25, wherein the fluid outlet of the fluid container is in fluid communication with a catholyte container.
27. (Previously Presented) The plating cell of claim 24, wherein the absorbent material is configured to leach additives into the electrolyte solution when the concentration of the additives is less than a desired concentration and to absorb additives from the electrolyte solution when the concentration is greater than the desired concentration.
28. (Previously Presented) The plating cell of claim 27, further comprising a filter positioned between the fluid container and the fluid basin, the filter being configured to remove particulate matter emanating from the absorbent material from a fluid stream passing therethrough.
29. (Previously Presented) An electrochemical plating cell, comprising:
a fluid basin configured to contain an electrolyte plating solution, the fluid basin having an anolyte fluid volume and a catholyte fluid volume, wherein the electrolyte plating solution comprises at least two solution additives;
a fluid tank in fluid communication with the fluid basin and being configured to supply the electrolyte plating solution thereto; and
an electrolyte solution stabilization device in fluid communication with the fluid tank, the stabilization device comprising:
a fluid container having a fluid inlet and a fluid outlet; and
an absorbent material positioned in the fluid container in a fluid path between the fluid inlet and the fluid outlet, wherein the absorbent material is configured to leach one solution additive into the electrolyte plating solution to maintain

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concentration of the one solution additive within a processing window during an electrochemical plating process.

30. (Previously Presented) The plating cell of claim 29, wherein the absorbent material comprises at least one of charcoal, polypropylene, glass, minerals, ion-exchange resins, resins for chromatography, and combinations thereof.

31. (Previously Presented) The plating cell of claim 29, wherein the anolyte volume is separated from the catholyte volume by a cationic membrane and the fluid outlet of the fluid container is in fluid communication with the catholyte container.

32. (Previously Presented) The plating cell of claim 30, wherein the absorbent material is configured to leach one solution additive into the electrolyte solution when the concentration of the additive is less than a desired concentration and to absorb additive from the electrolyte solution when the concentration is greater than the desired concentration.

33. (Previously Presented) The plating cell of claim 29, further comprising a filter positioned between the fluid container and the fluid basin, the filter being configured to remove particulate matter emanating from the absorbent material from a fluid stream passing therethrough.